

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-8 (canceled)

1 Claim 9. (original) A method of making a chip device, the method
2 comprising:
3 providing a die;
4 providing a leadframe including a die attach cavity and a plurality of dimples
5 defined around a periphery of the leadframe, the die attach cavity having substantially the
6 same thickness as the die;
7 placing solder balls into the dimples; and
8 flipping the die into the die attach cavity and attaching it therein.

1 Claim 10. (original) The method of claim 9 wherein the die provided is a
2 bumped die.

1 Claim 11. (new) The method of claim 9 wherein the die has solder balls
2 thereon to serve as source and gate connections.

1 Claim 12. (new) The method of claim 9 wherein the step of attaching the die
2 is performed such that the die is coplanar with a top surface of the leadframe.

1 Claim 13. (new) The method of claim 9 further comprising the step of adding
2 a solderable coating to the leadframe.

1 Claim 14. (new) The method of claim 9 wherein the leadframe is conductive.

1 Claim 15. (new) The method of claim 14 wherein the conductive leadframe
2 comprises a copper based alloy.